



SOT355-1

plastic thin shrink small outline package; 24 leads; body width 4.4 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	TSSOP24
Package type industry code	TSSOP24
Package style descriptive code	TSSOP (thin shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-153
Mounting method type	S (surface mount)
Issue date	19-2-2003

Table 1. Package summary

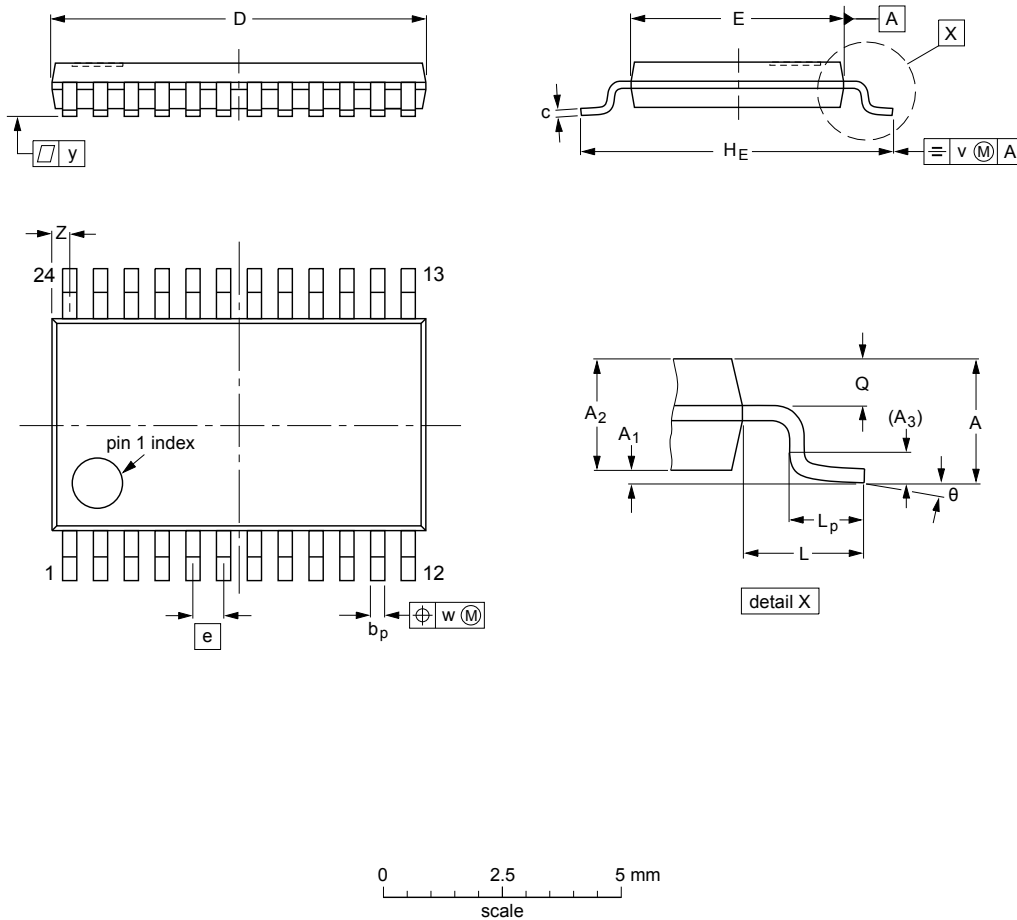
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	7.7	-	7.8	7.9	mm
E	package width	4.3	-	4.4	4.5	mm
A	seated height	[tbd]	-	1.1	1.1	mm
A ₂	package height	0.8	-	0.9	0.95	mm
n ₂	actual quantity of termination	-	-	24	-	



2. Package outline

TSSOP24: plastic thin shrink small outline package; 24 leads; body width 4.4 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	7.9 7.7	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT355-1		MO-153			99-12-27 03-02-19

Fig. 1. Package outline TSSOP24 (SOT355-1)

3. Soldering

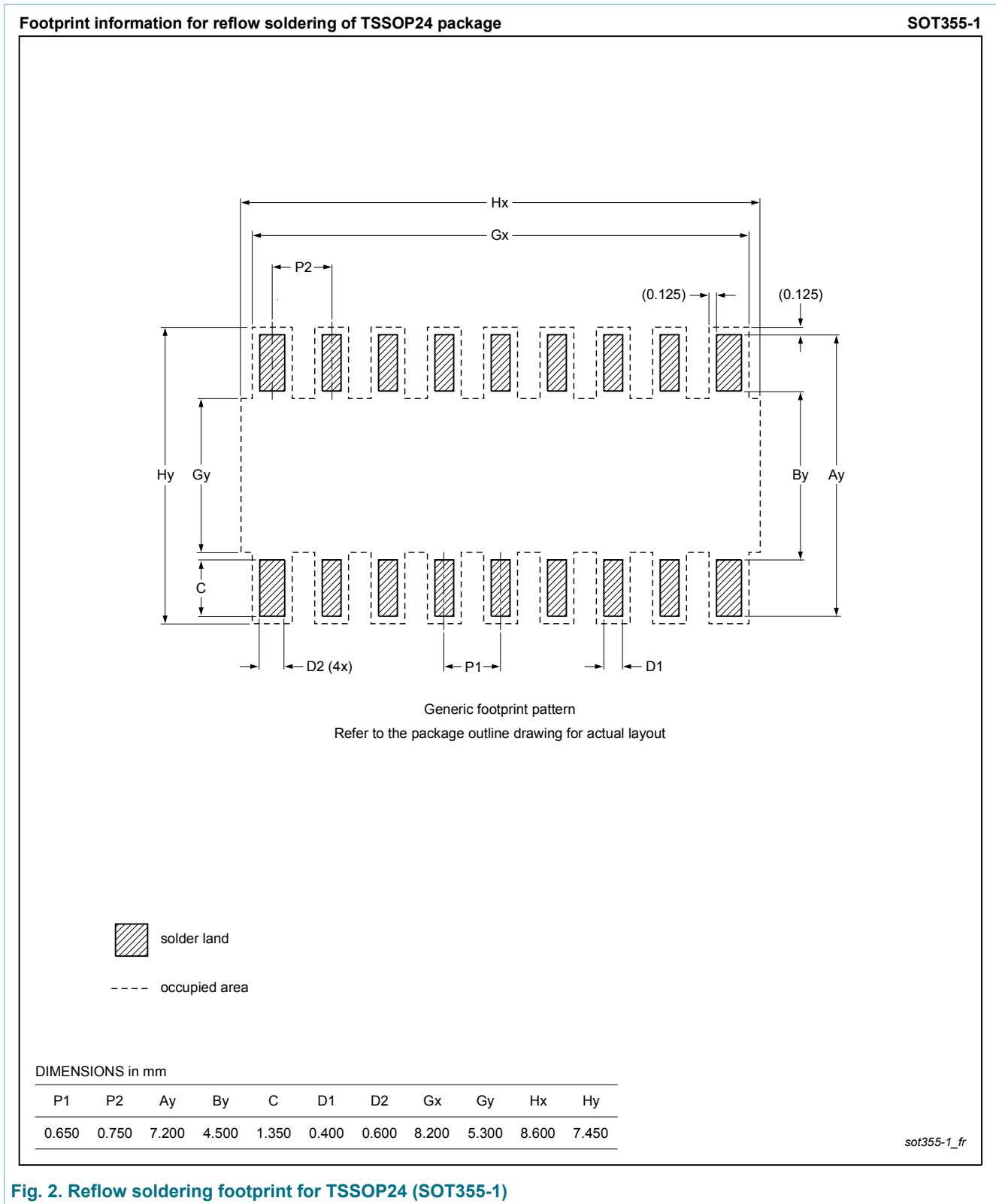
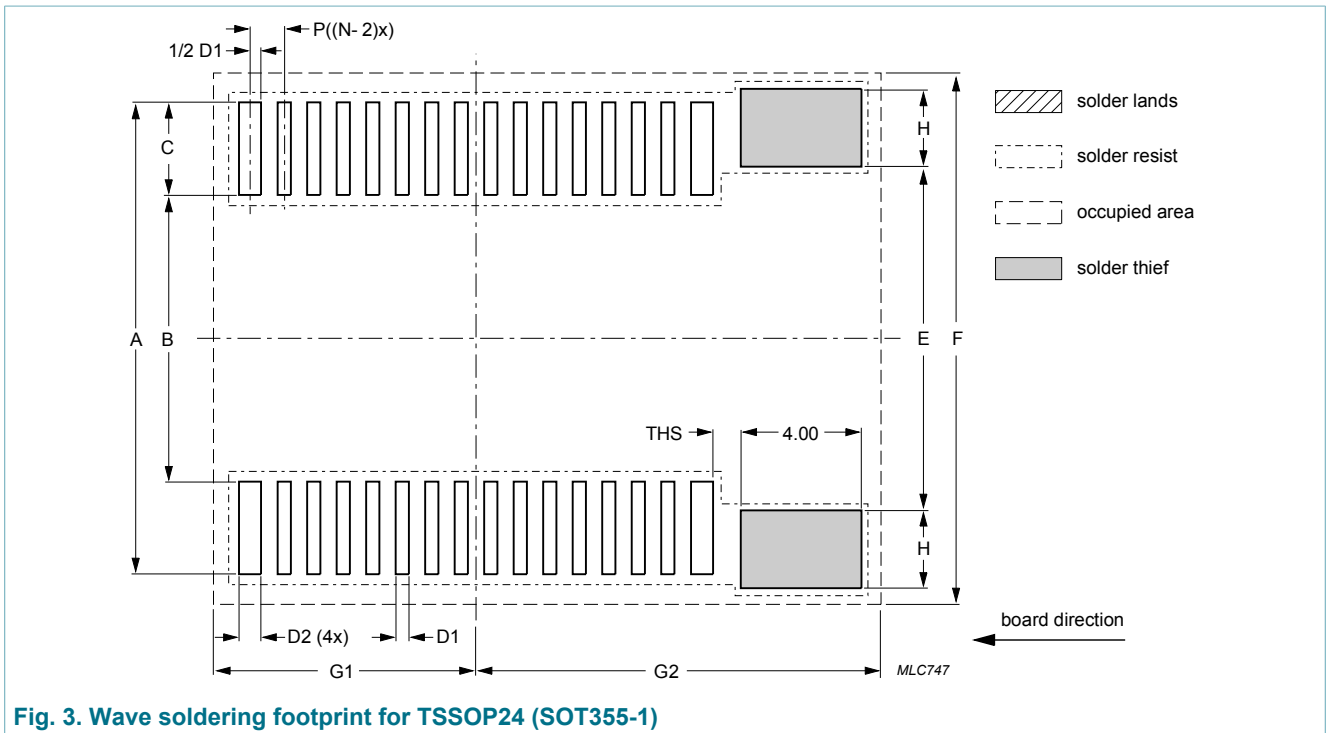


Fig. 2. Reflow soldering footprint for TSSOP24 (SOT355-1)

plastic thin shrink small outline package; 24 leads; body width 4.4 mm



4. Legal information

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